HPB8-49KYWHB (1W Day White, 4000K, 140Lm)

HUEY JANN High Power 1W LED is made of GaInN chips with precise package technique which makes excellent heat dissipation to reach the advantages of high luminous efficiency, low decay, and long endurance.

FEATURES

- Instant light
- Long operating life
- Superior ESD defense
- Low voltage DC operated
- More energy efficient than incandescent and most halogen lamps

TYPICAL APPLICATIONS

- Architectural detail lighting
- Portable flashlight
- Medical applications
- Beacon lights
- Decoration lights
- Spotlight

EXPLANATION OF PART NUMBER

H P B 8 - 4 9K WHB

① ② ③ ④ ⑤ ⑥ ⑦

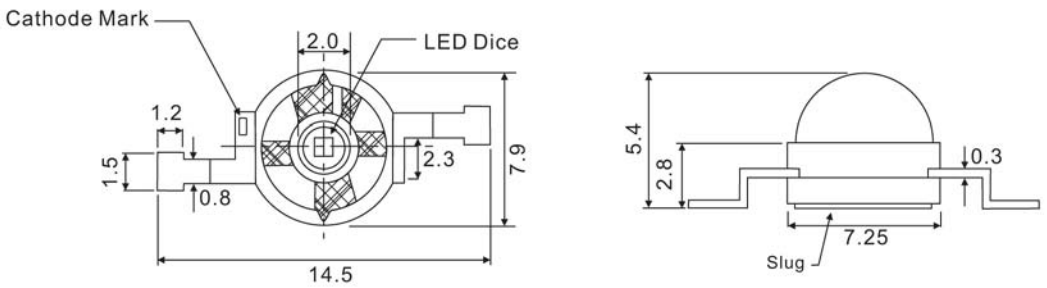
1. H: Huey Jann
2. P: High power LED Type
3. Shape distinguish:
   B: Lambertian type
4. Identification No:
5. Appearance:
   4:Water Clear
6. Color number:
   9K: White
7. Color kind:
   YWHB (4000°K):White

DEVICE

Item	Lens Color	Dice Source	Color Temperature Typ (°K)
HPB8-49KYWHB	Water Clear	GaInN/GaN	4000

PACKAGE DIMENSIONS

Emitter Type



NOTE:

1. All dimensions are in millimeter.
2. Lead spacing in measured where the lead emerge from the package.
3. Prodruced resin under flange is 1.5mm max.
4. Specifications are subject to change without notice.
5. Tolerance is ± 0.3mm unless otherwise noted.
6. Driving LED without heat sinking device is forbidden.
7. It is strongly recommended that the temperature of lead be not higher than 55°C.
8. Proper current derating must be observed to maintain junction temperature below the maximum.
9. LEDs are not designed to be driven in reserve bias.

ABSOLUTE MAXIMUM RATINGS

TA=25°C

PARAMETER	SYMBOL	MAX. RATING	UNIT
Continuous Forward Current	IF	350	mA
Peak Forward Current *1	IFM	500	mA
Electrostatic Discharge (HBM)	ESD	4000	V
LED Junction Temperature	Tj	135	°C
Operating Temperature	Topr	-40~+110	°C
Storage Temperature	Tstg	-40~+120	°C
Manual Soldering Temperature 260 °C for 5 seconds max. *2 *3			

**1. Duty Ratio=0.1%, Pulse Width=10us.*

**2. Iron soldering high temperature will not cause damage to the dice. But be aware of the high temperature will not only make the epoxy soften but also cause the lead moving and the gold wire broken and even open. So before returning to the normal temperatures PLEASE AVOID any serious pressure on the top of epoxy and lead.*

**3. Measured at leads, lens temperature must not exceed 120°C during lead soldering and slug attach. Soldering by general IR reflow, Vapor phase reflow and wave soldering on this system product is unsuitable. Selective heating of the leads limit lead soldering, such as by hot bar reflow, fiber focussed IR, or hand soldering. The package back plane (slug) may not be attached by soldering, but rather with a thermally conductive adhesive. Electrical insulation between the slug and the board is necessary. Please consult welding matters needing at tention.*

ELECTRIC-OPTICAL CHARACTERISTICS

TA=25°C

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
View Angle of Half Power	2θ1/2	IF=350mA		120		deg
Forward Voltage	VF			3.3	3.5	V
Thermal Resistance Junction to Case With Star Type Heat Sink	$R\theta_{J-C}$			15		°C/W
Thermal Resistance Junction to Case	$R\theta_{J-C}$			20		°C/W
Temperature Coefficient of Forward Voltage	$\Delta V_F/\Delta T$			-2		mV/°C

ELECTRIC-OPTICAL CHARACTERISTICS TO BE INDEPENDENT

IF=350mA TA=25°C

Item	CCT (°K)	CRI (Ra)	Brightness (lm)
	Typical		
HPB8-49KYWHB	4000	72	140

RELIABILITY TEST

Endurance Test

Test Item	Reference Standard	Test Conditions	Result
Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	Connect with a power If=350mA Ta=Under room temperature Test Time=1,000hrs	0/22
High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	Ta=+85°C±5°C RH=80% ~ 85% Test Time=1,000hrs	0/22
High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High Ta=+120°C±5°C Test Time=1,000hrs	0/22
Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=-40°C±5°C Test Time=1,000hrs	0/22

**Failure Criteria:*

1. VF arise ≥10%

2. IV decline ≥30%

3. A failure is an LED that is open or shorted

Environmental Test

Test Item	Reference Standard	Test Conditions	Result
Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	-40°C ~+25°C ~+85°C ~+25°C 60min 20min 60min 20min Test Time=200cycle	0/22
Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010	-40°C±5°C ~+110°C±5°C 20min 20min Test Time=200cycle	0/22

**Failure Criteria:*

1. VF arise ≥10%

2. IV decline ≥30%

3. A failure is an LED that is open or shorted

Brightness Bin Selection

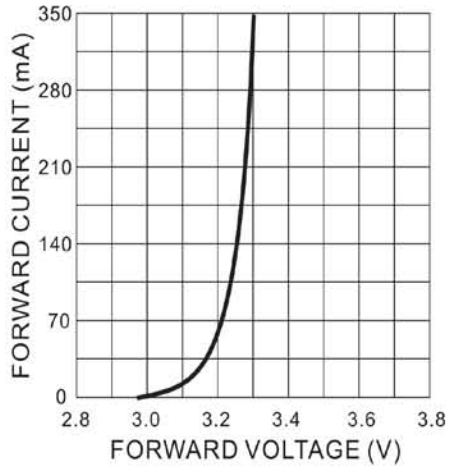
Item	BIN CODE	Brightness in lm	
		Minimum	Maximum
HPB8-49KYWHB	M	110	143
	N	143	186

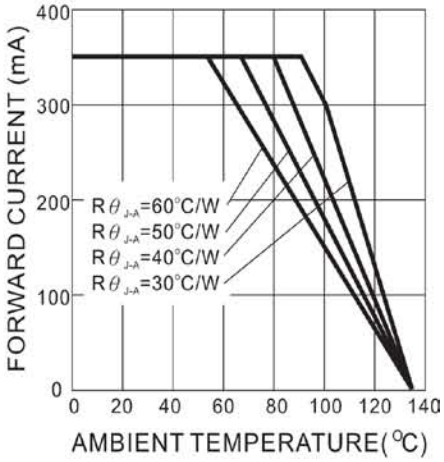
NOTE:

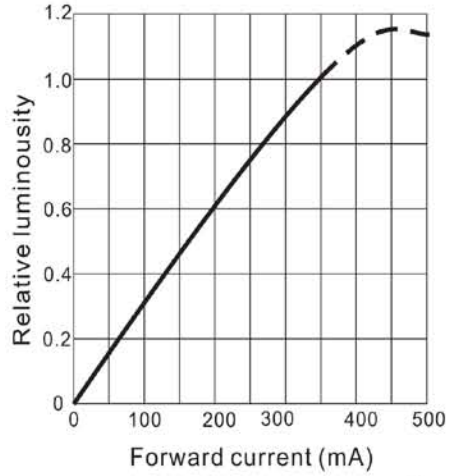
1. Test Condition at IF=350mA.

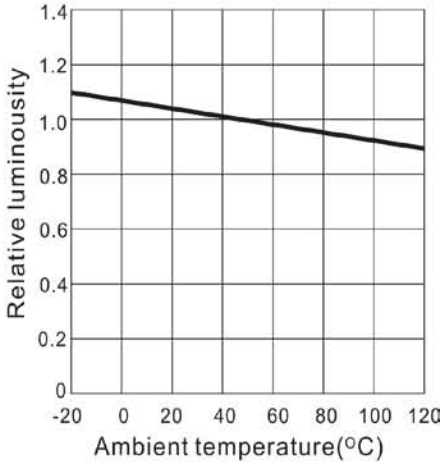
2. Brightness tolerance for each bin limit is ±15%

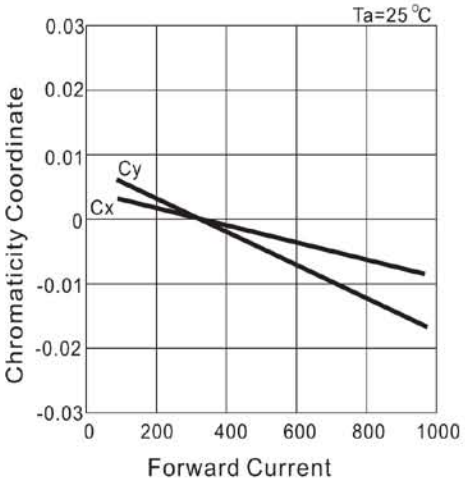
TYPICAL ELECTRICAL OPTICAL CHARACTERISTICS CURVES

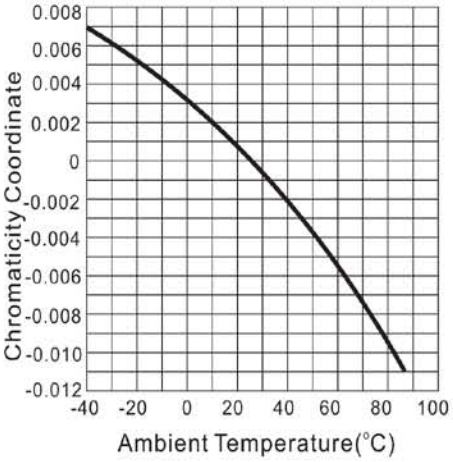


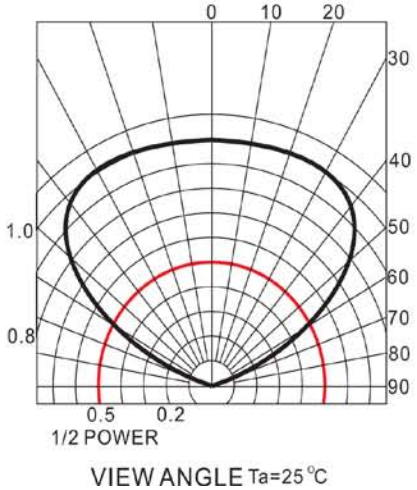


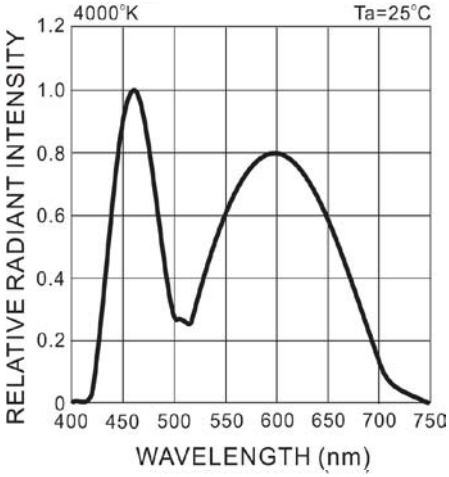








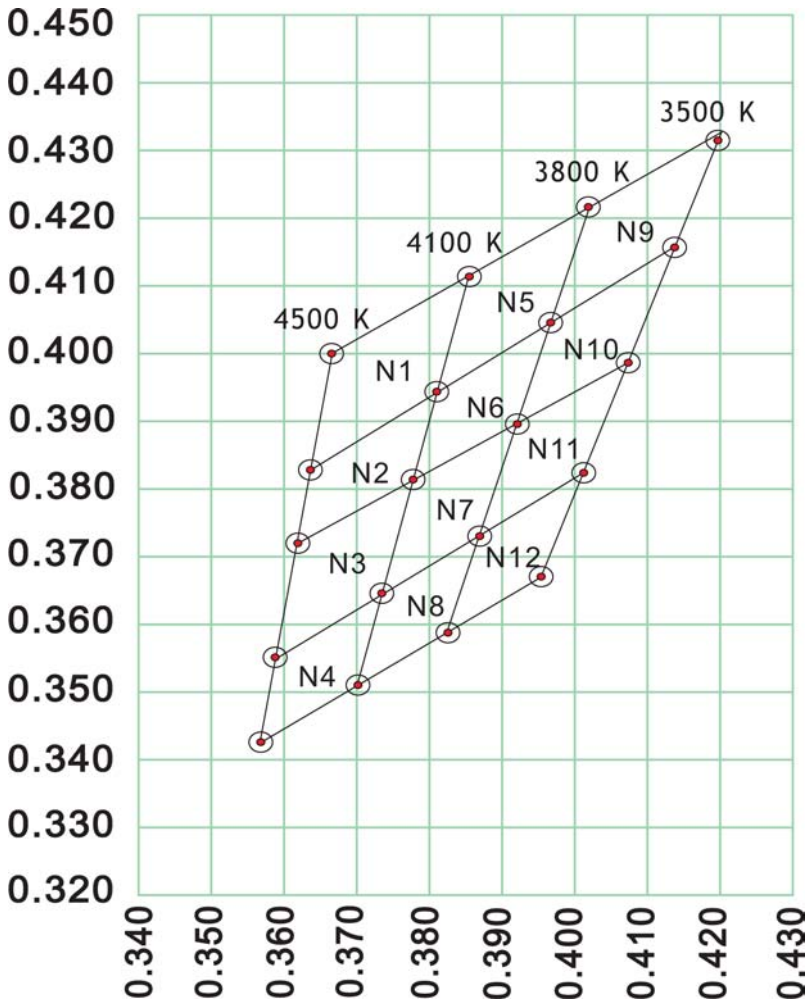




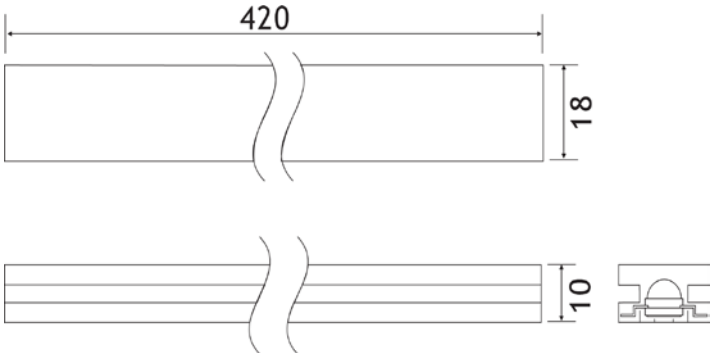
Nature White Color Bin Selection

Bin	CCT(°K) TYP	Chromaticity Coordinates				
N1	4300	x	0.367	0.385	0.381	0.364
		y	0.400	0.412	0.393	0.382
N2	4300	x	0.364	0.381	0.378	0.362
		y	0.382	0.393	0.382	0.371
N3	4300	x	0.362	0.378	0.374	0.359
		y	0.371	0.382	0.365	0.355
N4	4300	x	0.359	0.374	0.370	0.357
		y	0.355	0.365	0.351	0.342
N5	3950	x	0.385	0.402	0.396	0.381
		y	0.412	0.422	0.403	0.393
N6	3950	x	0.381	0.396	0.392	0.378
		y	0.393	0.403	0.390	0.382
N7	3950	x	0.378	0.392	0.387	0.374
		y	0.382	0.390	0.373	0.365
N8	3950	x	0.370	0.387	0.382	0.357
		y	0.351	0.373	0.359	0.342
N9	3650	x	0.402	0.420	0.414	0.396
		y	0.422	0.432	0.416	0.403
N10	3650	x	0.396	0.414	0.408	0.392
		y	0.403	0.416	0.399	0.390
N11	3650	x	0.392	0.408	0.402	0.387
		y	0.390	0.399	0.382	0.373
N12	3650	x	0.387	0.402	0.396	0.382
		y	0.373	0.382	0.367	0.359
Tolerance			x ± 0.02		y ± 0.02	

CIE Light Color Chart:



Package Dimension For Emitter Type



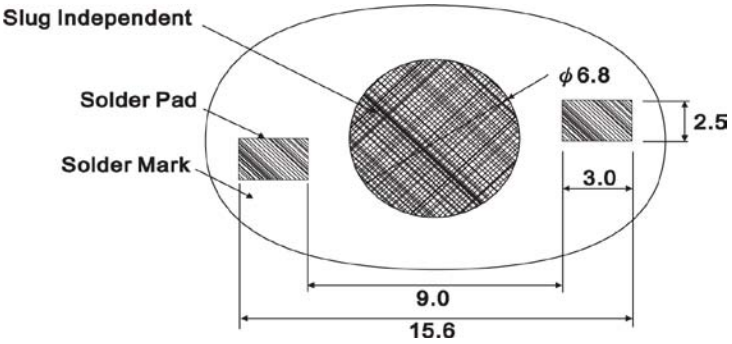
NOTE:

1. *Dimensions are specified as follows: mm.*
2. *Tolerance is ± 0.3mm unless otherwise noted.*
3. *50 pcs emitters per tube.*
4. *80 tubes per inside box.*
5. *4 inside box per outside box.*

Requirements to user For Emitter Type

The LED products by HUEY-JANN is designed, manufactured, and sold aiming at high standard quality and reliability, however, reliability of electronic apparatus is seen as a product of reliability superior to HUEY-JANN and using status at users. From this point, HUEY-JANN requests user's for following things.

Recommended Solder Pad Design For Emitter Type

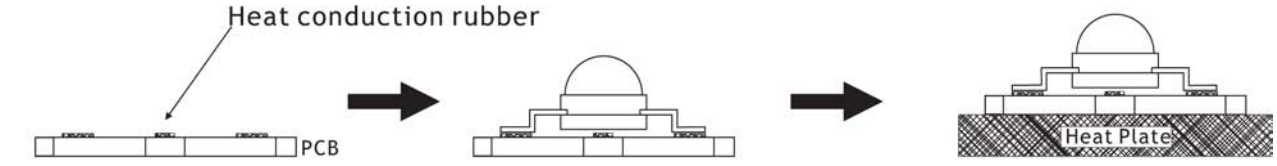


NOTE:

1. *All dimensions are in millimeters.*
2. *Electrical isolation is required between Slug and Solder Pad.*

Heat Plate Soldering Condition For Emitter Type

a. Soldering Process for Solder Paste



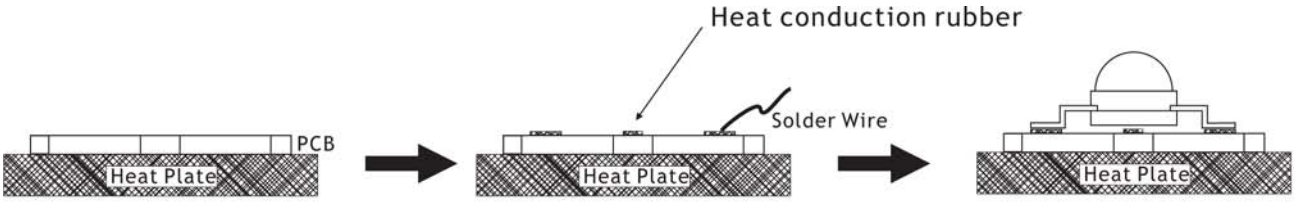
Use Solder Mask to print Solder Paste on PCB.

Place Emitter on PCB.

Put PCB on Heat Plate until Solder Paste melt.

1. The Solder Paste sould be melted within 10 seconds.
2. Take out PCB out from Heat Plate within 15 seconds.

b. Soldering Process for Solder Wire



Put PCB on Heat Plate.

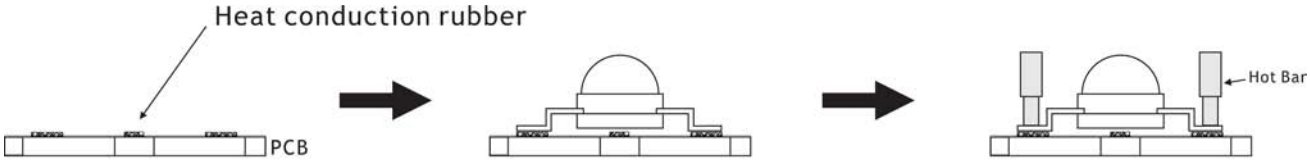
Place Solder Wire to the solder pad of PCB.

Put Emitter on PCB. Take the PCB out from Heat Plate within 10 seconds.

NOTE:

1. *Heat plate temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.*
2. *When soldering, do not put stress on the LEDs during heating.*
3. *After soldering, do not warp the circuit board.*

Soldering Process For Hot Bar For Emitter Type



Thermal Conductive Glue Dispensing

Put Emitter on the PCB.

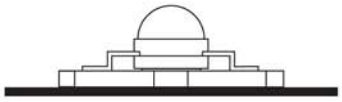
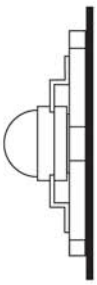
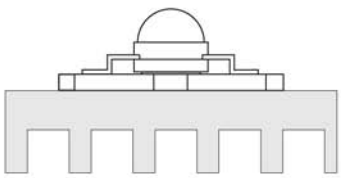
Hot Bar soldering of High Power Emitter

NOTE:

1. *Hot Bar temperature: 230°C max for Lead Solder and 260°C max for Lead-Free Solder.*
2. *When soldering, do not put stress on the LEDs during heating.*
3. *After soldering, do not warp the circuit board.*

Conclusion

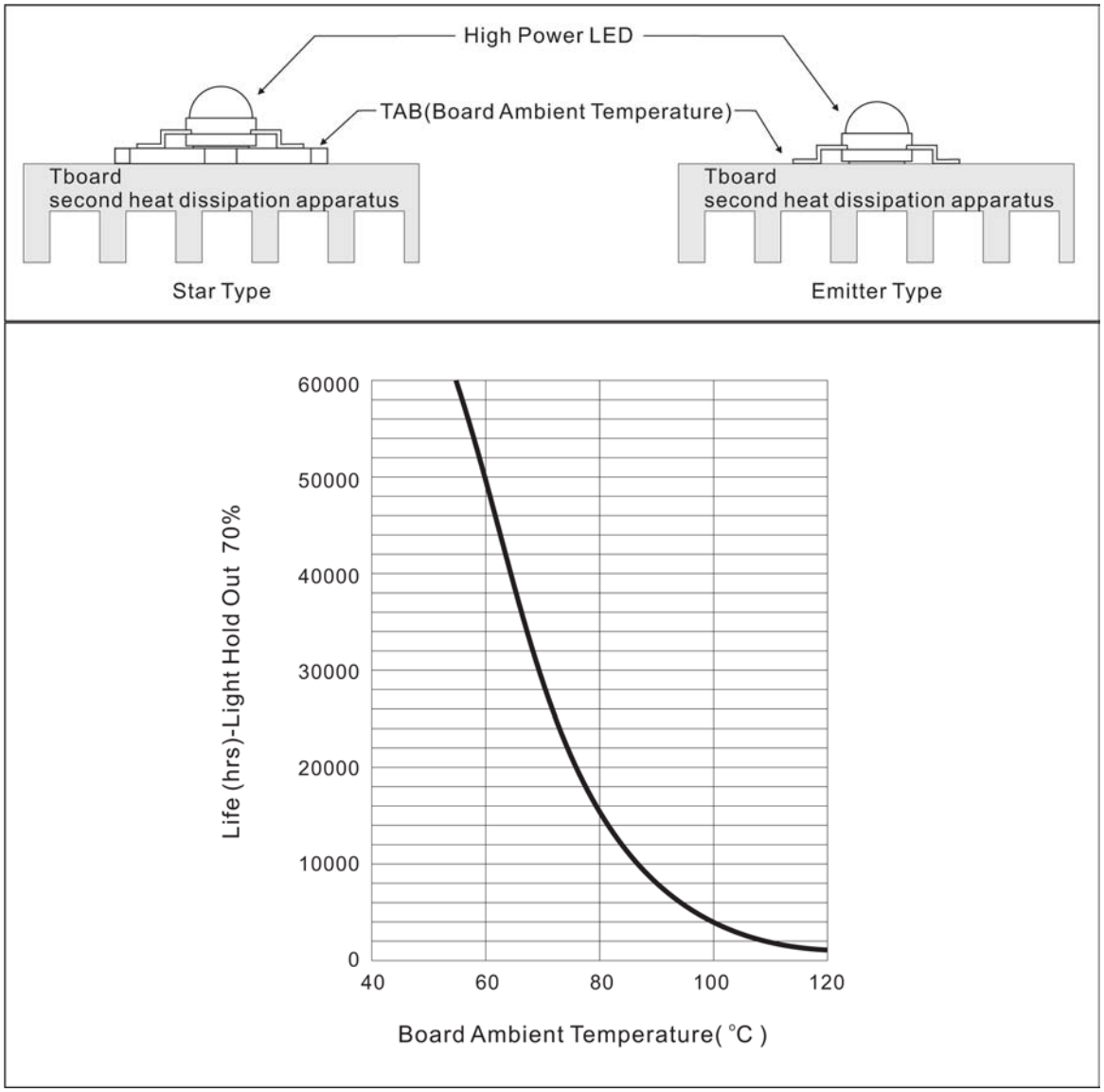
Huey Jann provide simple comparison table for High Power LED, you could find your request heat dissipation area from the following table.

	 Free Convection Horizontal Flat Heat Dissipation-Set-up (Area Require mm^2)	 Free Convection Vertical Flat Heat Dissipation-Set-up (Area Require mm^2)	 Free Convection Finned Heat Dissipation-Set-up (Area Require mm^2)
1W	1,800	1,500	2,400

** TAB in this table is according to highest operating temperature 65°C.*

** Different materials of second heat dissipation device, the surface area of heat sink will be different. Thus, this document is for reference only.*

TAB Temperature - Life Characteristics Curves



** Board Ambient Temperature Tolerance ±5°C.*

** TAB in this table is according to highest operating temperature 65°C.*

** The TAB is the stable testing value for the product lighted 100% after one hour.*

** Different materials of second heat dissipation device, the surface area of heat sink will be different. Thus, this document is for reference only.*